


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/19/10633	
1.3 Title of PCN	STM32H743, STM32H753 & STM32H750 products - new die revision	
1.4 Product Category	STM32H743, STM32H753 & STM32H750 products	
1.5 Issue date	2019-04-07	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
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2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign: Mask or mask set change with new die design - Design changes in active elements.	Crolles 300

4. Description of change

	Old	New
4.1 Description	<p>STM32H743, STM32H753 & STM32H750 : revision Y</p> <ul style="list-style-type: none"> - Datasheet DS12110 Revision 5 for STM32H743xl products - Datasheet DS12117 Revision 5 for STM32H753xl products - Datasheet DS12556 Revision 2 for STM32H750VB & STM32H750IB & STM32H750XB products <p>Limitations are described in Errata sheets :</p> <ul style="list-style-type: none"> - Errata sheet ES0392 Revision 4 for STM32H743xl products - Errata sheet ES0396 Revision 4 for STM32H750xB and STM32H753xl products 	<p>STM32H743, STM32H753 & STM32H750 : new die revision V</p> <ul style="list-style-type: none"> - Datasheet DS12110 Revision 6 for STM32H743xl products - Datasheet DS12117 Revision 6 for STM32H753xl products - Datasheet DS12556 Revision 3 for STM32H750VB & STM32H750IB & STM32H750XB products <p>Limitations are described in Errata sheets :</p> <ul style="list-style-type: none"> - Errata sheet ES0392 Revision 5 for STM32H743xl products - Errata sheet ES0396 Revision 5 for STM32H750xB and STM32H753xl products <p>ST MCD Division is pleased to announce features of STM32H743, STM32H753 & STM32H750 products will be enhanced through the introduction of new die revision.</p> <ul style="list-style-type: none"> • All system issues fixed (refer to errata sheets). • ADC improvements allowing better performances and efficient concurrent usage. • Fixed IP limitations (refer to errata sheets).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Function : improvements are indicated in Datasheets and errata sheets	

5. Reason / motivation for change

5.1 Motivation	The strategy of ST MCD Division is to increase the robustness and improve performances, quality and functionality of our products. This is achieved by introducing new die revision for STM32H743, STM32H753 & STM32H750 products.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	The die revision change, see table in 10633 Detailed description document attached. It is marked onto the package of the part.
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7. Timing / schedule	
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7.1 Date of qualification results	2019-03-19
7.2 Intended start of delivery	2019-04-19
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
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8.1 Description	10633 PCN10633_Die_450XXXV_Qualification_plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-04-07

9. Attachments (additional documentations)	
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10633 Public product.pdf
10633 PCN10633_Die_450XXXV_Qualification_plan.pdf
10633 PCN10633_Additional information.pdf

10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H753IIK6	

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